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FORM PTO-1596
1-31-92

U.S. DEPARTMENT OF COMMERCE
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DOCKET NO.: INTEL-0000

102739472
PATENTS ONLY

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereto:

16834 U.S. PTO
10/836329



050304

1. Name of conveying party(ies):
Chia-Pin CHIU S-3-04
Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):
Name: INTEL CORPORATION
Internal Address:
Street Address: 2200 Mission College Blvd.
City: Santa Clara
State/Country: California, U.S.A. ZIP: 95054
Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other
Execution Date: April 30, 2004

4. Application number(s) or patent number(s): 10836329
If the document is being filed together with a new application, the execution date of the application is: April 30, 2004
A. Patent Application No(s). Filed:
B. Patent No(s)
Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: FLESHNER & KIM, LLP
Internal Address:
Street Address: P. O. Box 221200
City: Chantilly State: VA ZIP: 20153-1200

6. Total number of applications and patents involved: 1
7. Total fee (37 C.F.R. 3.41)..... \$40.00
 Enclosed (Check No. 11839)
 Authorized to be charged to deposit account
8. Deposit account number:
16-0607

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Garth D. Richmond, Reg. No. 43,044 [Signature] May 3, 2004
Name and Registration No. of Person Signing Signature Date
Total number of pages including cover sheet: 3

CMB No. 0851-0011 (exp. 4/94)

05/06/2004 MGETACHE 00000118 10836329
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PATENT
REEL: 015294 FRAME: 0410

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged Chia-Pin CHIU, the undersigned, hereby sell, assign, and transfer to Intel Corporation a corporation of Delaware, having a principal place of business at 2200 Mission College Blvd., Santa Clara, CA 95052, ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements that are disclosed in the application for the United States patent that has been executed by the undersigned prior hereto or concurrently herewith on the dates indicated below and is entitled ENHANCED STACK-DIE PACKAGE DESIGN BY DIRECT THERMAL LINKAGE FROM DIE TO PCB,

and in and to said application and all divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original patents, reissued patents, reexamination certificates, and extensions, that have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

agree that said Assignee may apply for and receive a patent or patents for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements, and all applications for

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Each Inventor: Please Sign and Date Below:

<u>4-30</u> , 20 <u>04</u> Date	<u><i>Chia-Pin Chiu</i></u> Name: Chia-Pin CHIU
_____, 20____ Date	_____ Name:
_____, 20____ Date	_____ Name:
_____, 20____ Date	_____ Name:
_____, 20____ Date	_____ Name:
_____, 20____ Date	_____ Name:

Each Inventor: Please also list the date that you signed the accompanying DECLARATION AND POWER OF ATTORNEY:

<u>4-30</u> , 20 <u>04</u> Date
_____, 20____ Date
_____, 20____ Date
_____, 20____ Date
_____, 20____ Date
_____, 20____ Date